COMPLIANT

HALOGEN

FREE



N-Channel 150 V (D-S) MOSFET



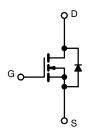
PRODUCT SUMMARY						
V _{DS} (V)	150					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0079					
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.0085					
Q _g typ. (nC)	35.1					
I _D (A)	77.4					
Configuration	Single					

FEATURES

- TrenchFET® Gen V power MOSFET
- Very low R_{DS} x Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} x Q_{oss} FOM
- 100 % R_a and UIS tested
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Synchronous rectification
- · Primary side switch
- DC/DC converters
- Power supplies
- Motor drive control



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SiR570DP-T1-RE3

ABSOLUTE MAXIMUM RATING	iS (1 _A = 25 °C, u	inless other	vise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	150	V	
Gate-source voltage		V_{GS}	± 20	V	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		77.4		
	T _C = 70 °C	1 .	61.9		
	T _A = 25 °C	I _D	19 ^{b, c}		
	T _A = 70 °C		15.2 ^{b, c}	^	
Pulsed drain current (t = 100 µs)		I _{DM}	200	A	
	T _C = 25 °C		94		
Continuous source-drain diode current	T _A = 25 °C	l _S	5.6 ^{b, c}		
Single pulse avalanche current	I 0.1 mill	I _{AS}	30		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	45	mJ	
	T _C = 25 °C		104		
Maximum power dissipation	T _C = 70 °C		66.6	14/	
	T _A = 25 °C	P _D	6.25 ^{b, c}	W	
	T _A = 70 °C		4 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) c		Ĭ.	260	-0	

THERMAL RESISTANCE RATING	GS				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	15	20	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	0.9	1.2	C/VV

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- See solder profile (www.vishav.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 54 °C/W
- g. $T_C = 25$ °C

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	150	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	125	-	m 1/0	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-6.9	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	-	4	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	=	100	nA	
Zoro gata voltaga drain aurrant	,	V _{DS} = 120 V, V _{GS} = 0 V	-	-	1		
Zero gate voltage drain current	I _{DSS}	V_{DS} = 120 V, V_{GS} = 0 V, T_{J} = 70 °C	-	-	15	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α	
Drain-source on-state resistance ^a	D	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.0065	0.0079	Ω	
Diani-Source on-State resistance "	R _{DS(on)}	$V_{GS} = 7.5 \text{ V}, I_D = 15 \text{ A}$	-	0.0070	0.0085	52	
Forward transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 20 A	-	80	_	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	3740	-		
Output capacitance	C _{oss}	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	330	-	pF	
Reverse transfer capacitance	C _{rss}		-	6.5	-		
Total gate aboves	Q_{g}	$V_{DS} = 75 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	46.9	71		
Total gate charge	Qg		-	35.1	53		
Gate-source charge	Q_{gs}	$V_{DS} = 75 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 20 \text{ A}$	-	18.1	-	nC	
Gate-drain charge	Q_{gd}		-	4.2	-		
Output charge	Q _{oss}	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}$	-	111	-		
Gate resistance	Rg	f = 1 MHz	0.4	1.1	1.8	Ω	
Turn-on delay time	t _{d(on)}		-	17	34		
Rise time	t _r	$V_{DD} = 75 \text{ V}, R_L = 3.75 \Omega, I_D \cong 20 \text{ A},$	-	16	32		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	29	58		
Fall time	t _f		-	21	42	no	
Turn-on delay time	t _{d(on)}		-	21	42	ns	
Rise time	t _r	$V_{DD} = 50 \text{ V}, R_L = 3.75 \Omega, I_D \cong 20 \text{ A},$	-	74	148		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 7.5 \text{ V}, R_g = 1 \Omega$	-	27	54	-	
Fall time	t _f		-	22	44		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	94	Α	
Pulse diode forward current	I _{SM}		-	-	200	A	
Body diode voltage	V _{SD}	I _S = 5 A, V _{GS} = 0 V	-	0.75	1.1	V	
Body diode reverse recovery time	t _{rr}		-	84	168	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	221	442	nC	
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}\text{C}$	-	65	-		
Reverse recovery rise time	t _b			19	_	ns	

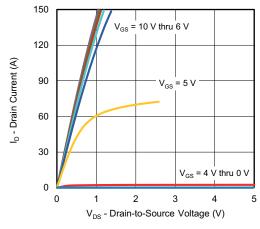
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

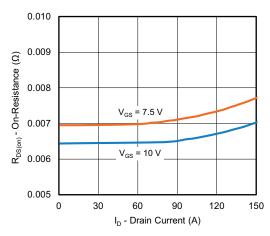
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



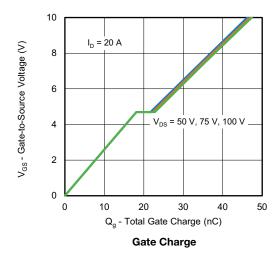
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

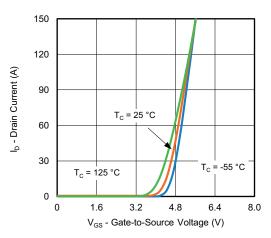


Output Characteristics

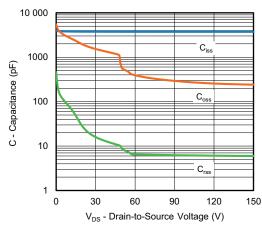


On-Resistance vs. Drain Current and Gate Voltage

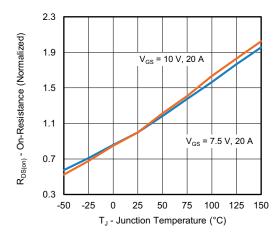




Transfer Characteristics



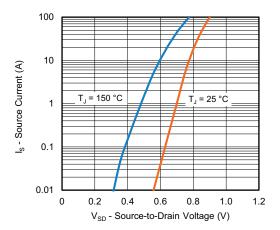
Capacitance



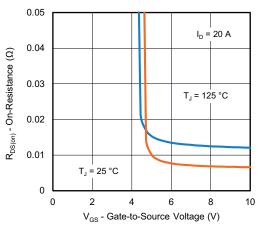
On-Resistance vs. Junction Temperature



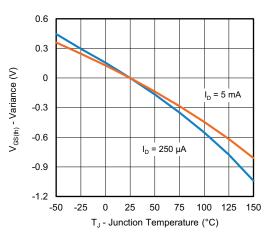
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



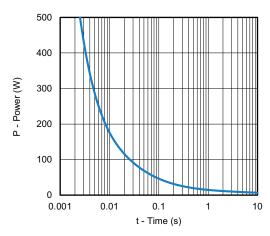
Source-Drain Diode Forward Voltage



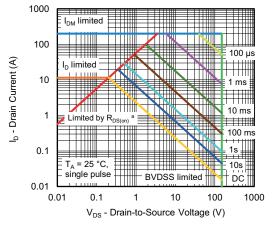
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient



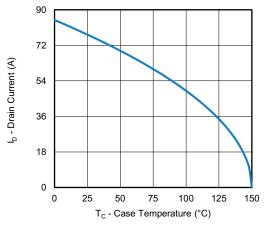
Safe Operating Area, Junction-to-Ambient

Note

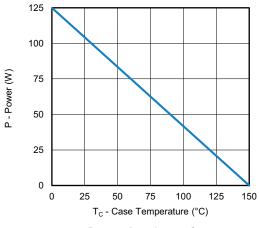
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



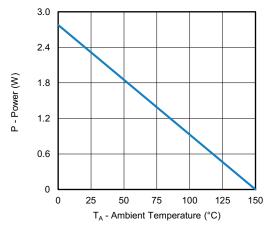
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating a



Power, Junction-to-Case



Power, Junction-to-Ambient

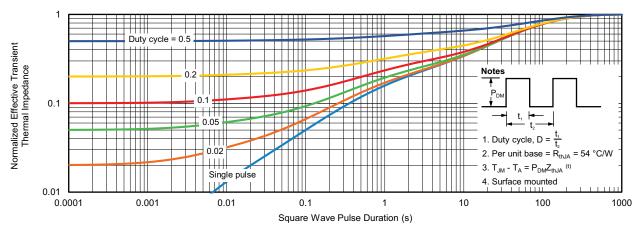
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

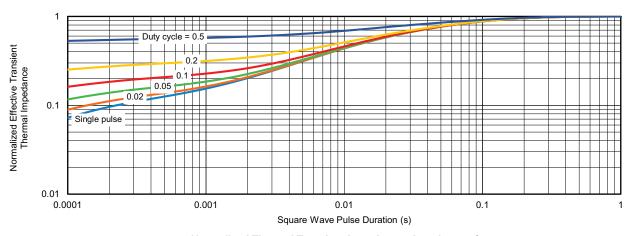


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

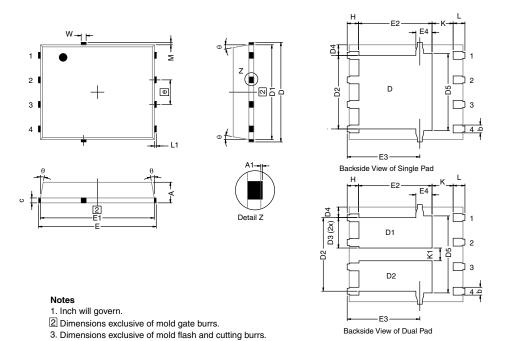


Normalized Thermal Transient Impedance, Junction-to-Case

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PowerPAK® SO-8, (Single/Dual)

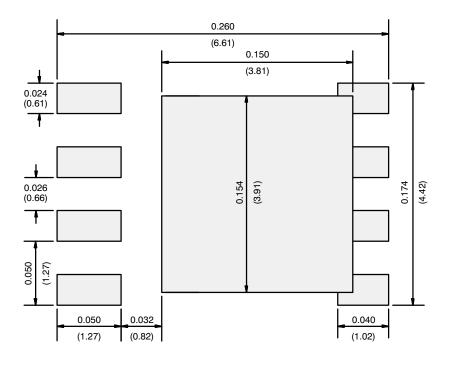


DIM.		MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX		
Α	0.97	1.04	1.12	0.038	0.041	0.044		
A1		-	0.05	0	-	0.002		
b	0.33	0.41	0.51	0.013	0.016	0.020		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	5.05	5.15	5.26	0.199	0.203	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.56	3.76	3.91	0.140	0.148	0.154		
D3	1.32	1.50	1.68	0.052	0.059	0.066		
D4		0.57 typ.		0.0225 typ.				
D5		3.98 typ.			0.157 typ.			
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	5.79	5.89	5.99	0.228	0.232	0.236		
E2	3.48	3.66	3.84	0.137	0.144	0.151		
E3	3.68	3.78	3.91	0.145	0.149	0.154		
E4		0.75 typ.			0.030 typ.			
е		1.27 BSC		0.050 BSC				
K		1.27 typ.		0.050 typ.				
K1	0.56	-	-	0.022	-	-		
Н	0.51	0.61	0.71	0.020	0.024	0.028		
L	0.51	0.61	0.71	0.020	0.024	0.028		
L1	0.06	0.13	0.20	0.002	0.005	0.008		
θ	0°	=	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.014		
M	0.125 typ.			0.005 typ.				

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RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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